

ABSTRACT**METHOD AND DEVICE FOR BLEED OUT CONTROL****IN SOLDER BONDING**

An improved die placement and bonding apparatus with bleed out control for attachment of a die onto the prescribed surface of a leadframe. The apparatus contains a bond frame provided with an alignment mechanism, and a die placement mechanism. The frame has a perimeter side wall with a base defining a predetermined area therein, with dimensions larger than the dimensions of the die. The side wall is used to provide a solder liquid tight seal when it is placed on a prescribed surface of the leadframe. The alignment mechanism is coupled to the frame and allows the frame to be properly aligned with the leadframe before it is lowered onto the prescribed surface. The die placement mechanism is used for delivering and placing the die onto the liquid solder on the leadframe within the side wall.

FIGURE 3A